

New developments in LED components for SSL

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III-nitride semiconductors

And the “blue” came in the early 90’s
with III-V nitrides (Al,Ga,In)N



1993

S. Nakamura



1995

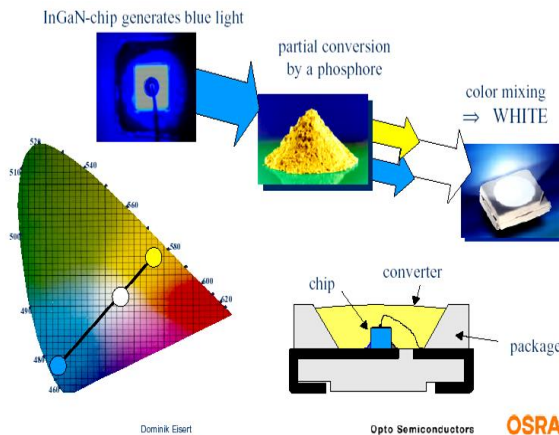
S. Nakamura



UV, blue, and green LEDs Color displays, High density DVD

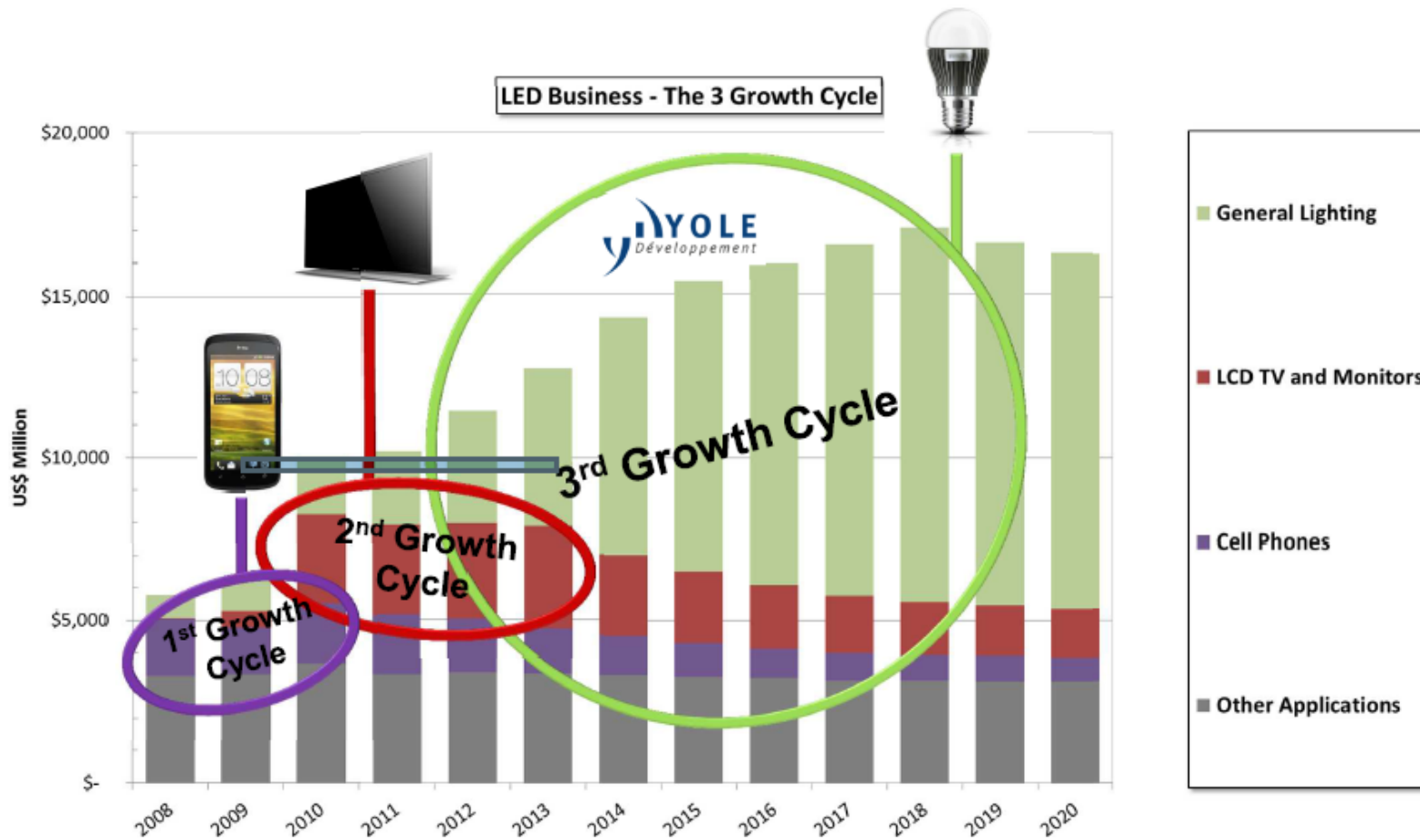


White LEDs



**GaN is the
building block
of Solid State
Lighting**

White LED market



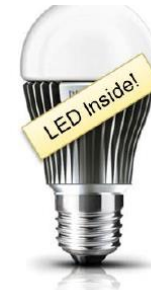
White LEDs: cost issue



Incandescent
< \$1



Fluorescent
~ \$3-\$5



LED
~ \$10 - \$30¹

$$\text{COST} = \frac{\$}{\text{LUMEN}}$$

Manufacturing Efficiency

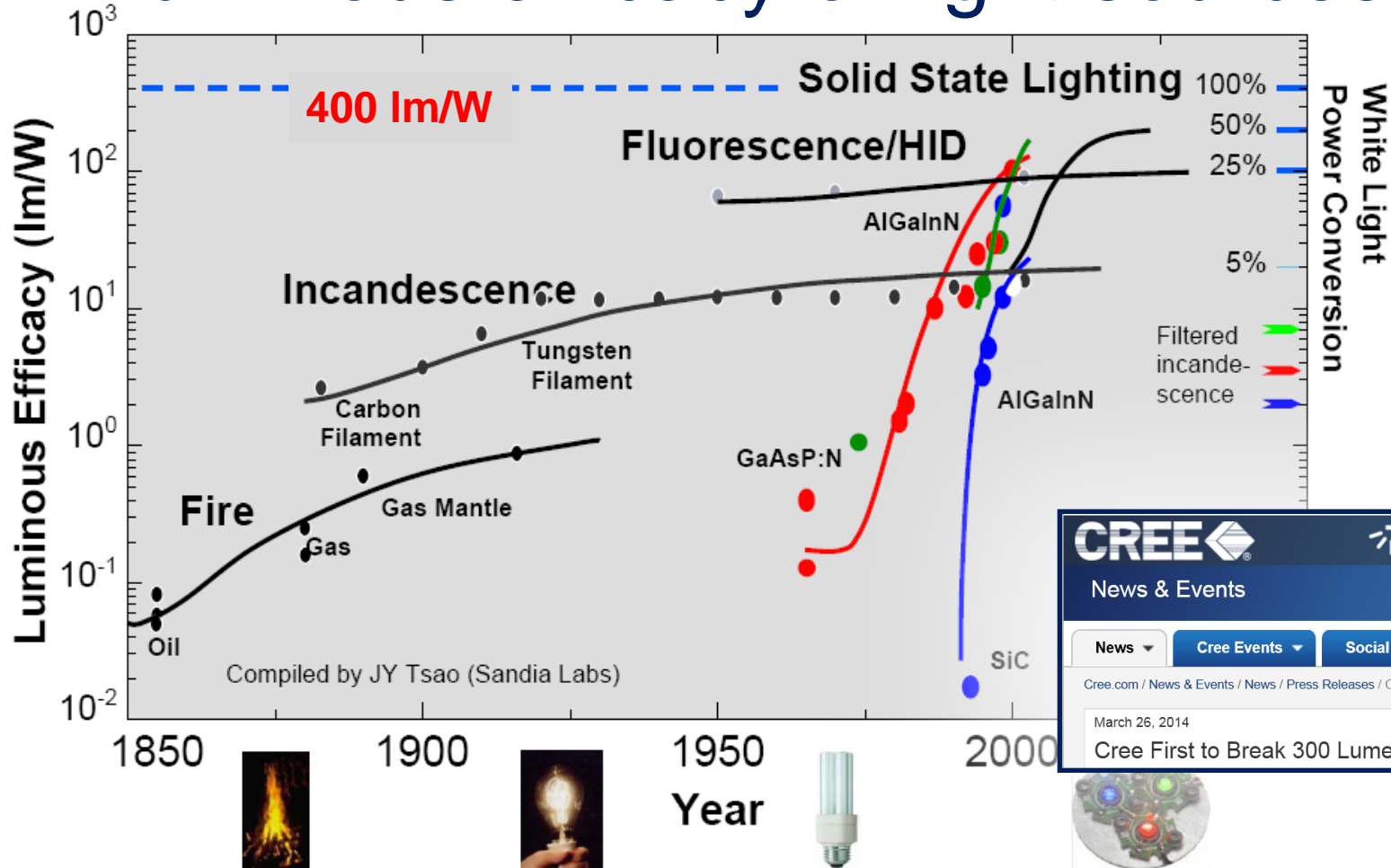
- Higher equipment throughput and yields
 - Dedicated equipment
 - Economy of scale
- x3

LED Performance

- Higher efficiency (lumen/W)
 - More light per chip (driving current)
- x2

Light source efficacy

Luminous efficacy of light sources

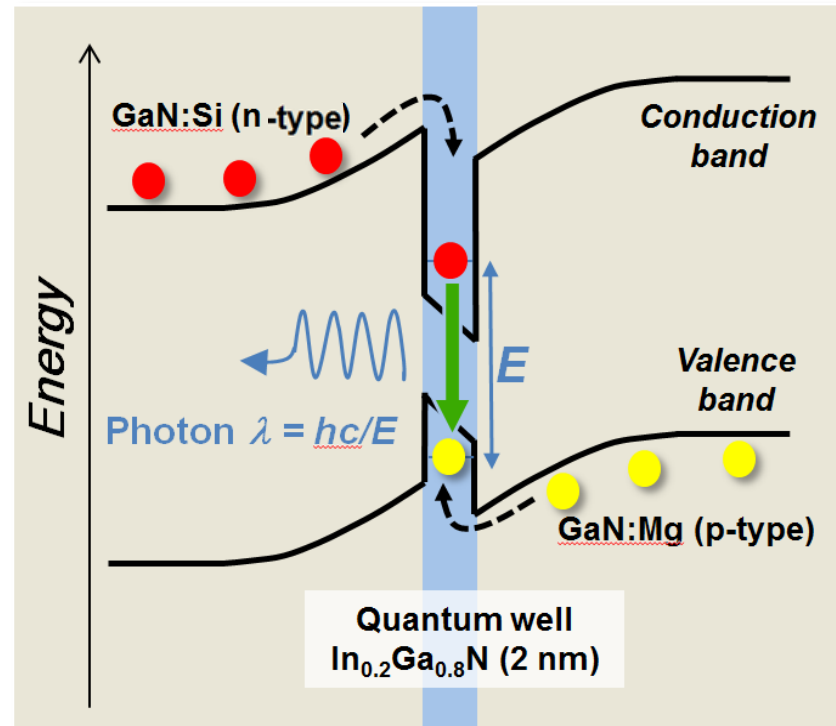
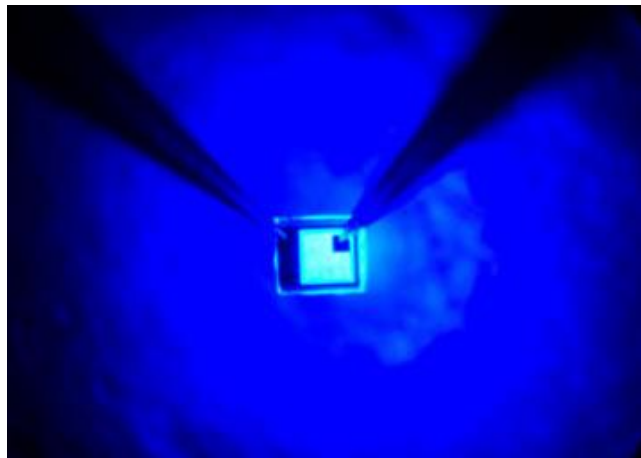
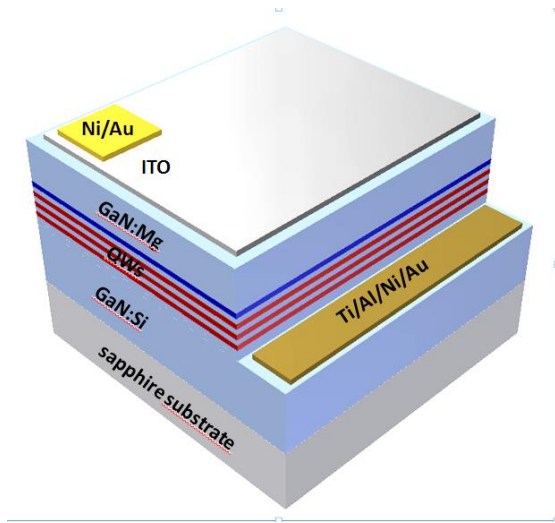


Incandescent lamp: 15 lm/W
Fluorescent lamp: 50-100 lm/W

LED lamp: 100 lm/W

Solid state lighting with GaN

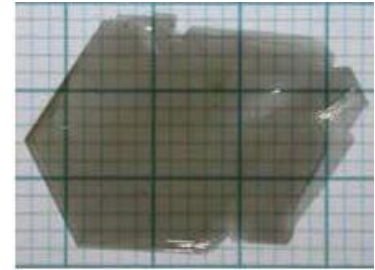
How can we make such high efficiency LEDs ?
and how do they work ?



Growth of III-V nitrides

Lack of GaN bulk substrates

produced only at Unipress (PL) - 1 cm²



GaN technology has been developed on foreign substrates

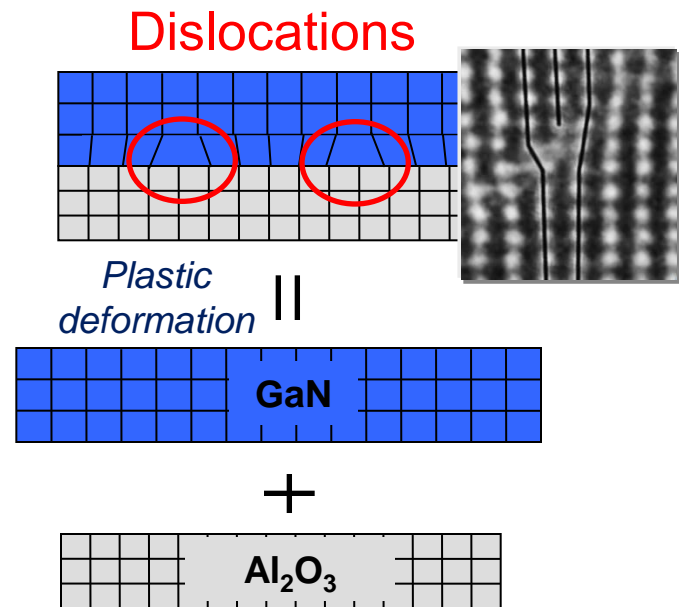
⇒ Large Lattice mismatch

Al_2O_3 (0001): +16 %

6H-SiC (0001): -3,5 %

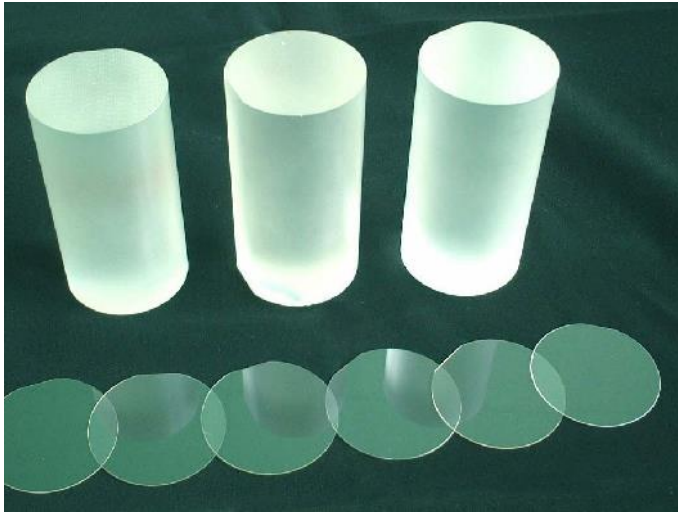
Si (111): -17 %

(GaAs/Si: +4 %)

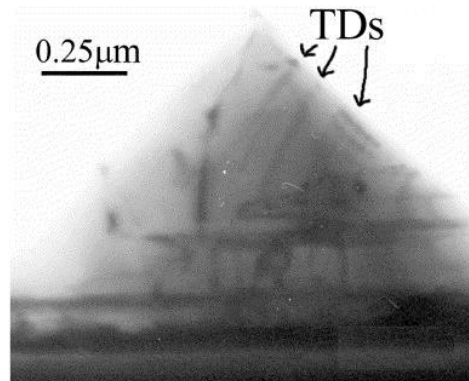
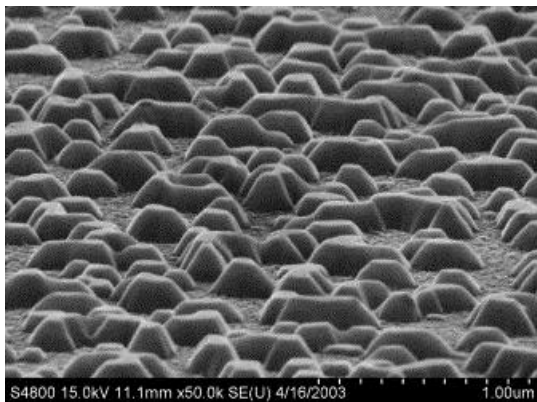
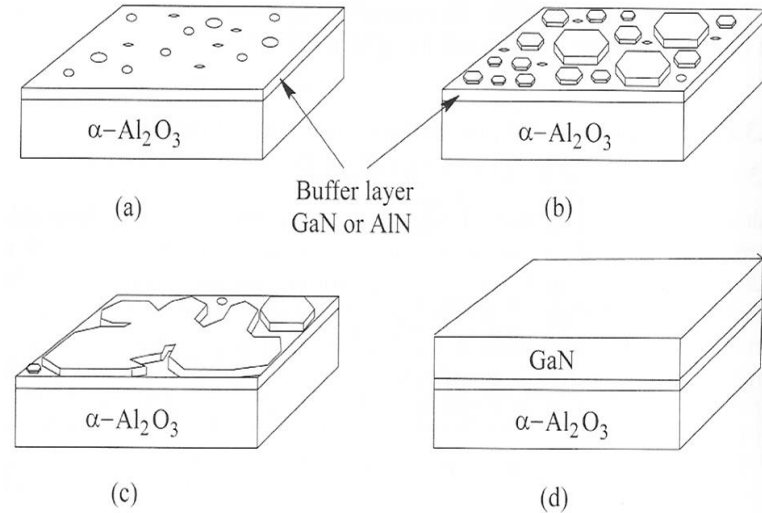


Hetero-Epitaxial Growth ⇒ Dislocations

Epitaxial growth of III-V nitrides



Most commonly used substrate: sapphire (0001)

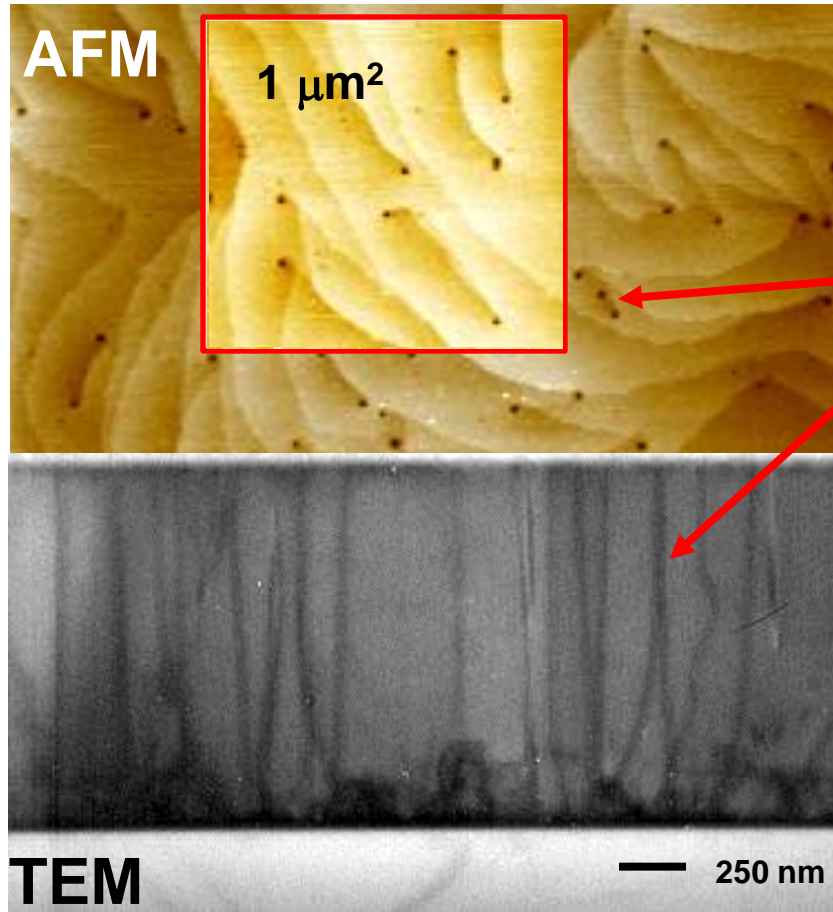


Two-step growth procedure

- 1) a thin buffer layer (25 nm) deposited at low-temperature (500°C) and further annealed
- 2) growth at high-temperature ($1050\text{-}1100^\circ\text{C}$)

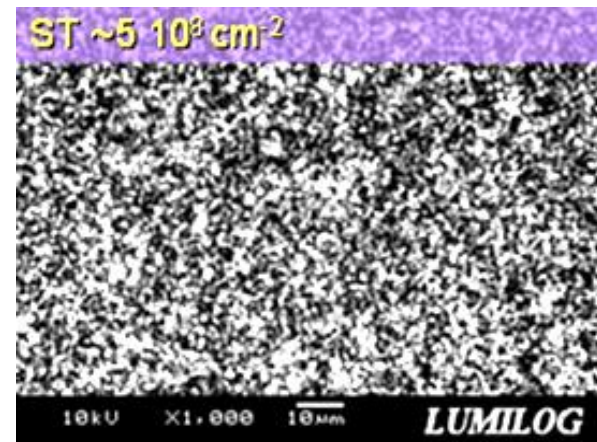
Epitaxial growth of III-V nitrides

High dislocation density: $1-10 \times 10^8 \text{ cm}^{-2}$



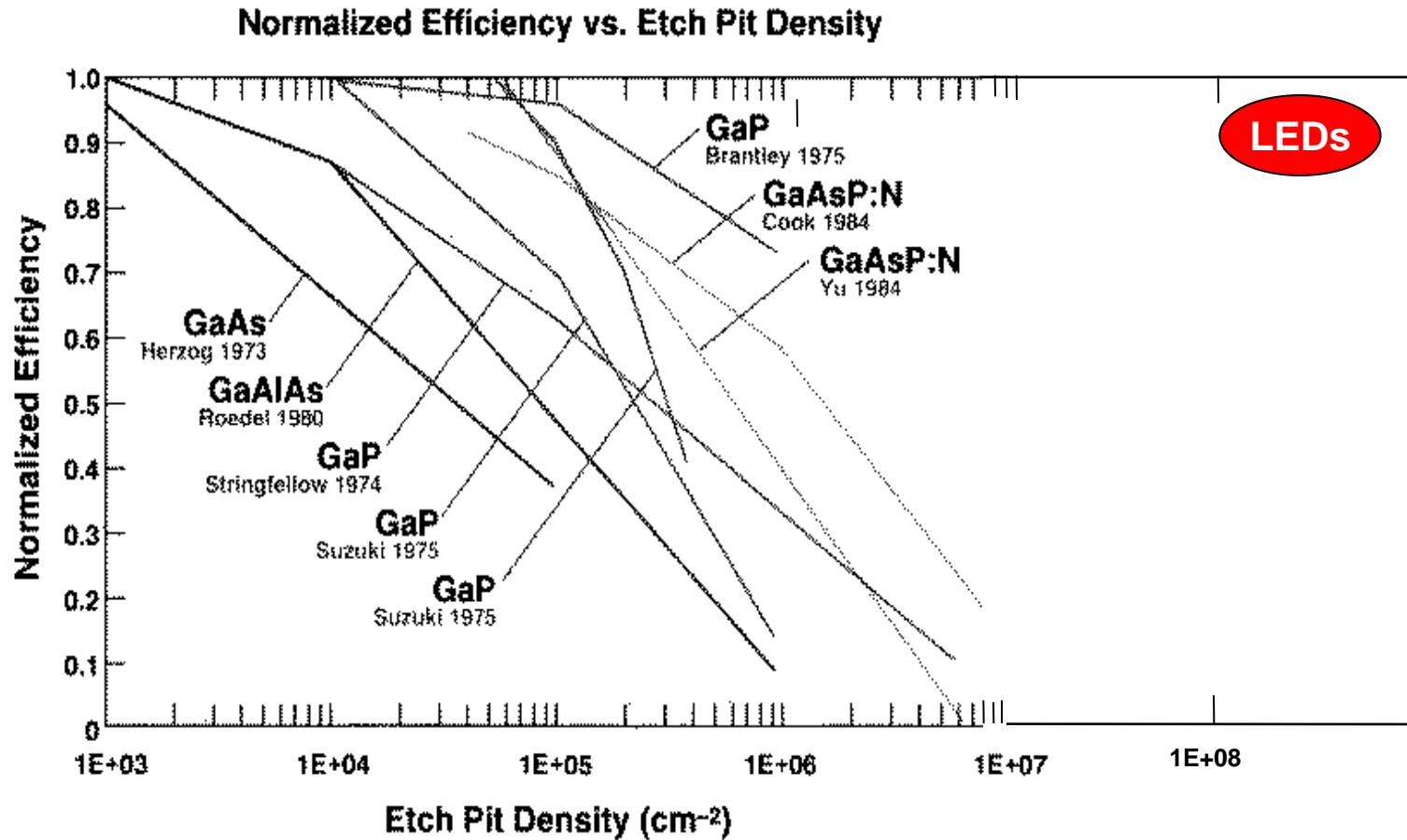
Surface

Dislocations



Cross-section

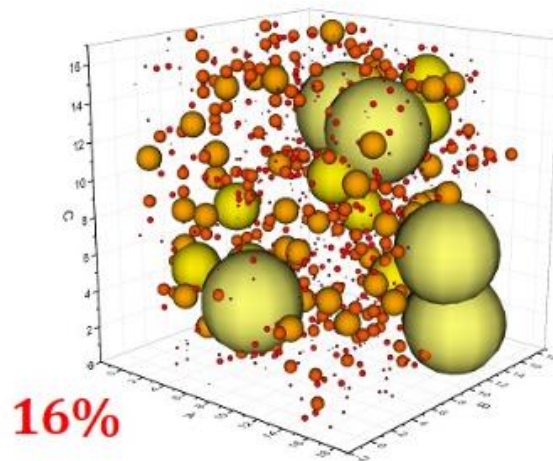
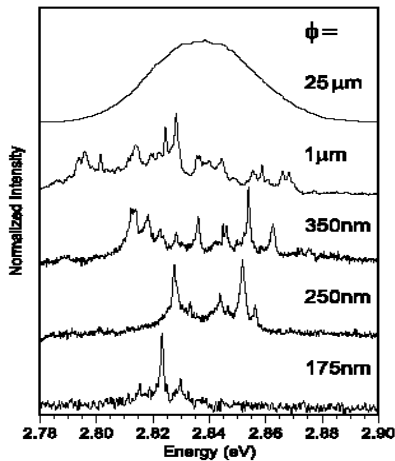
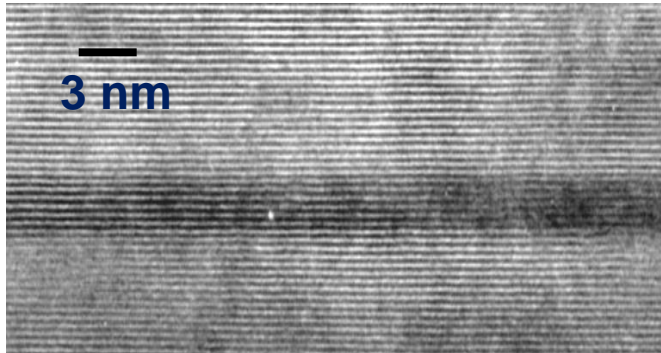
LED efficiency



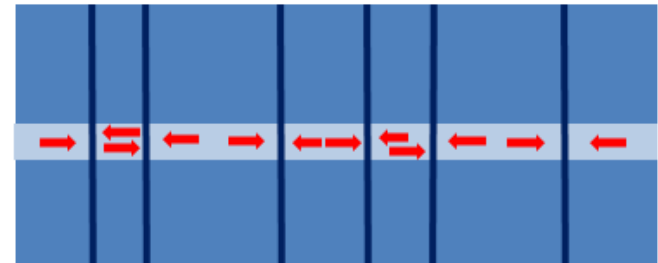
- 1 – LEDs: high efficiency (IQE>90%) despite high density of defects
- 2 - LEDs are less sensitive than LDs to the presence of dislocations

LED efficiency

Efficiency of a defective medium



Carriers in a quantum well



Carriers in quantum dots



Gérard and Weisbuch (patent 1990)

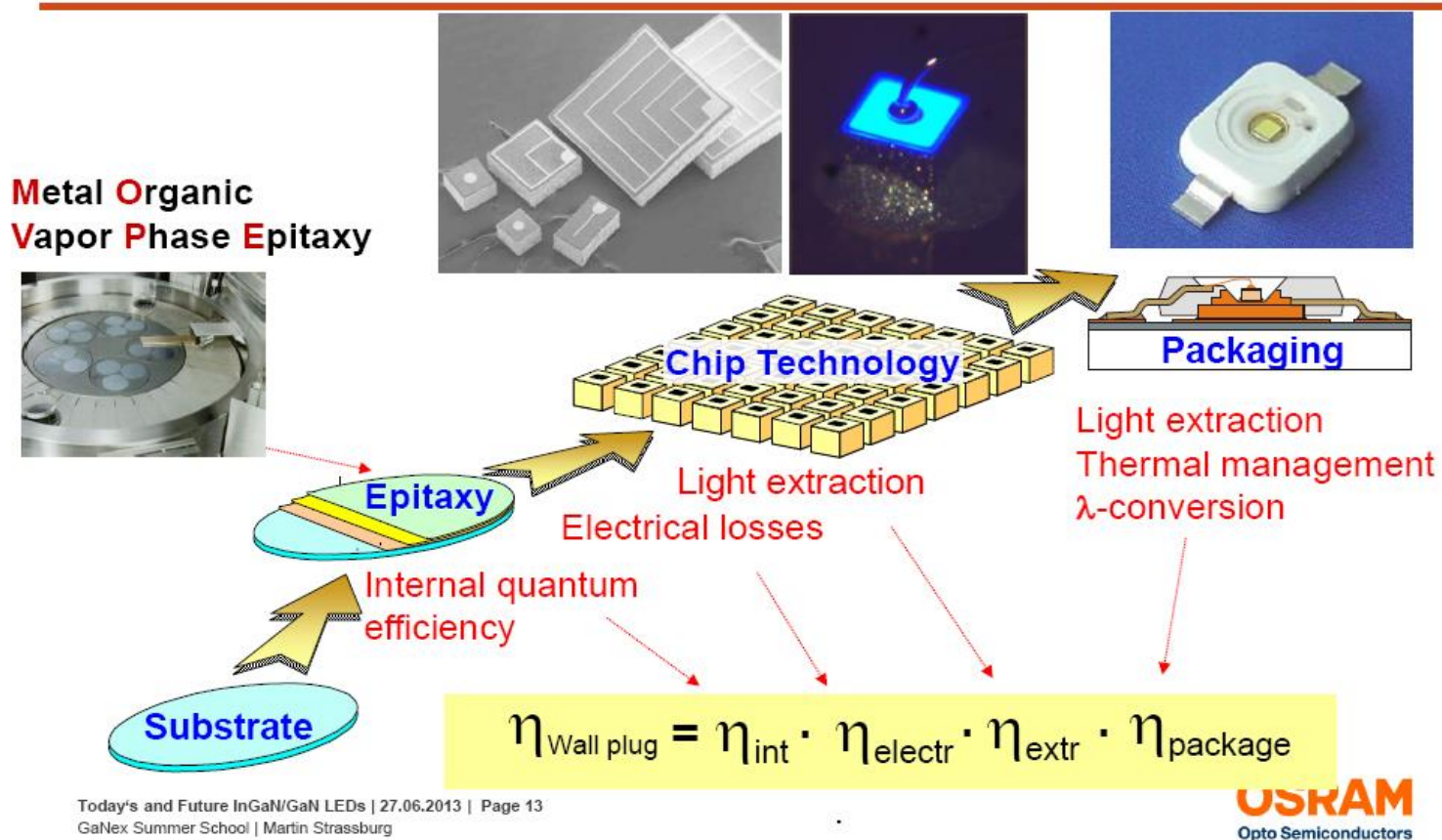
Schömig *et al*, PRL (2004)

Carrier localization prevents radiative efficiency collapse

IQE > 95%

Current technology – LEDs

HB-LED Technology: process chain



Today's and Future InGaN/GaN LEDs | 27.06.2013 | Page 13
GaNex Summer School | Martin Strassburg

USRAM
Opto Semiconductors

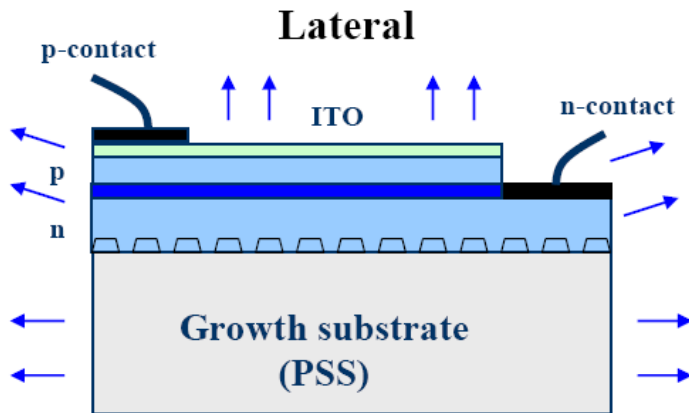
Blue LEDs: IQE > 90% Ext. Eff. > 85% EQE = 80%
Wall plug efficiency (WPE) > 60%

LED efficiency: light extraction

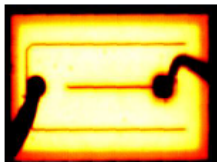
Pre-dominant Nitride chip designs



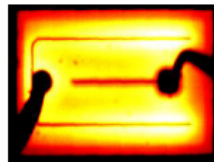
Lateral and Vertical chip designs prevail in selected applications



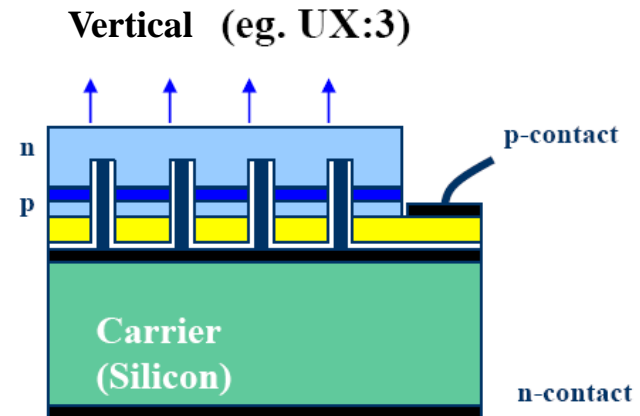
Low current



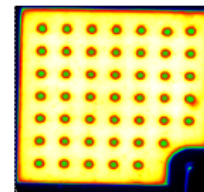
High current



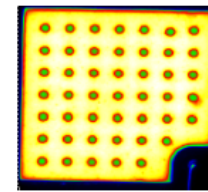
Limited current distribution



Low current



High current



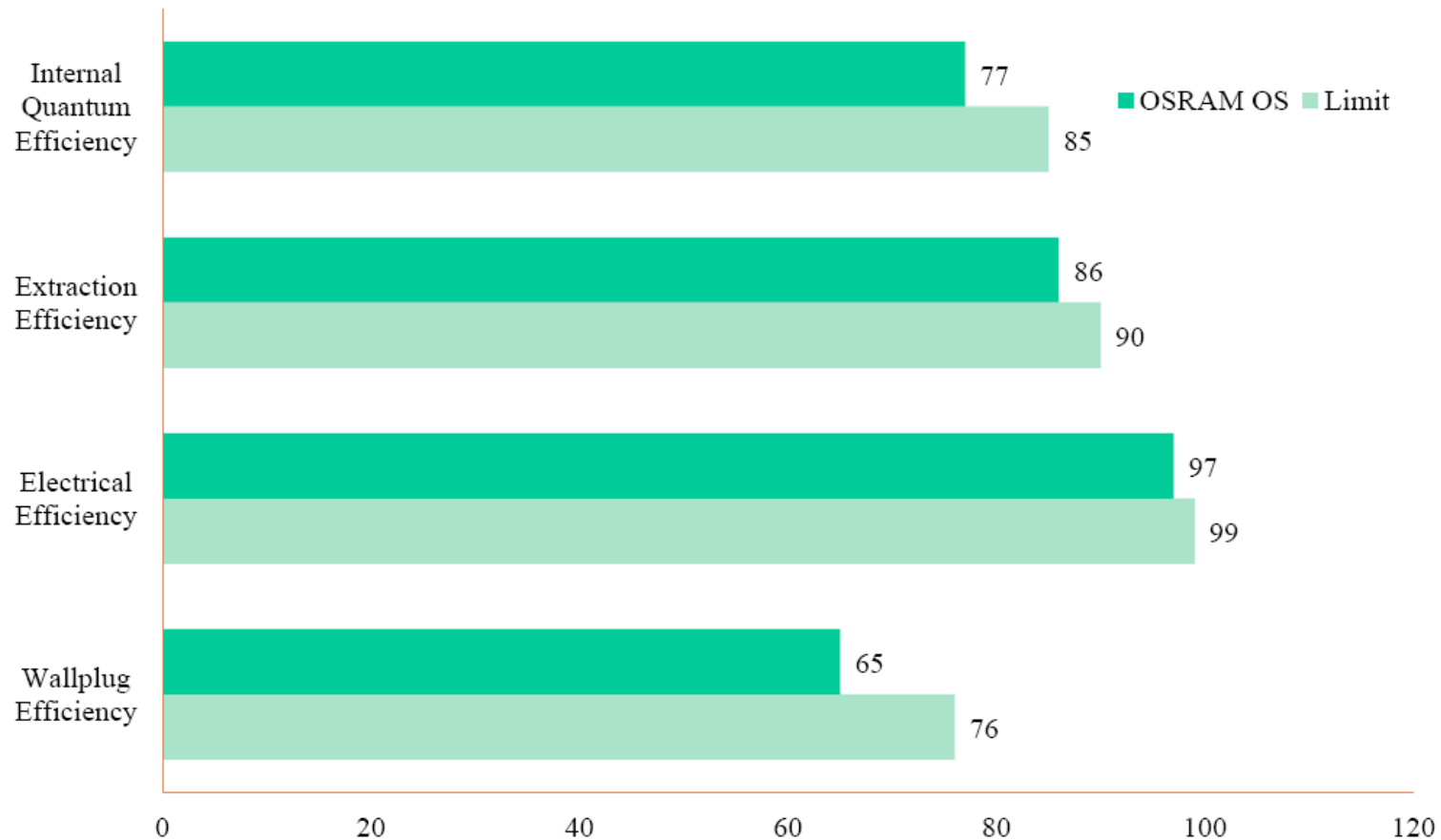
Maximum lumen output per chip area

LED efficiency

Efficacy Split - Current Status

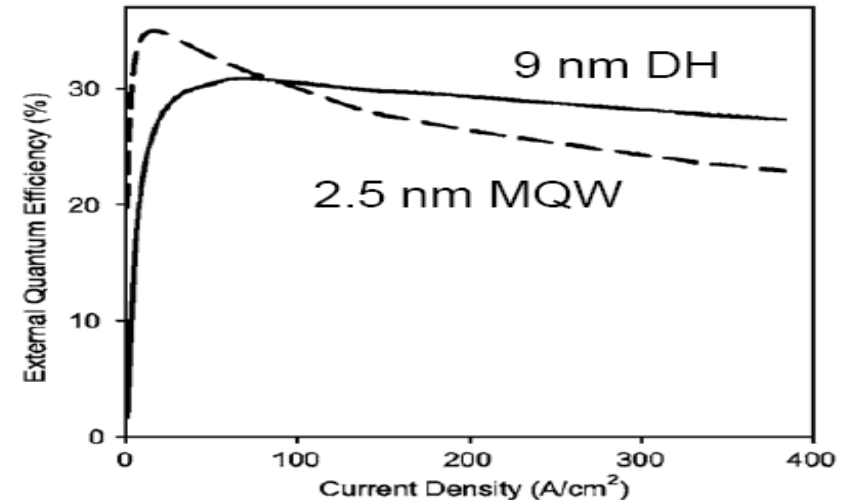
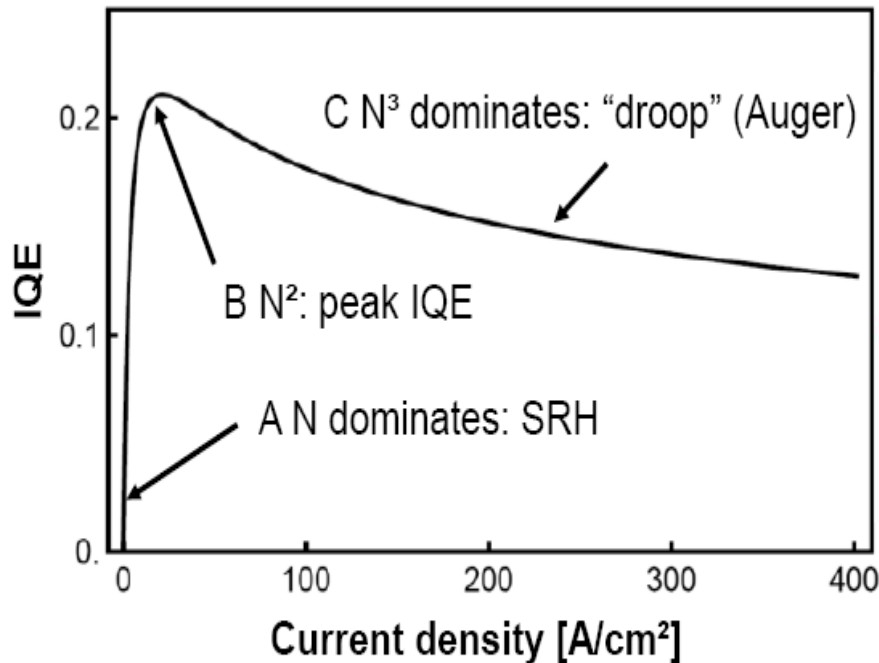
OSLON Square (3000 K, CRI 80) at 350 mA, 85°C;

OSRAM
Opto Semiconductors



LEDs – Challenges and perspectives

IQE – droop – green gap



Gardner, et al., Appl. Phys. Lett. **91**, 243506 (2007)

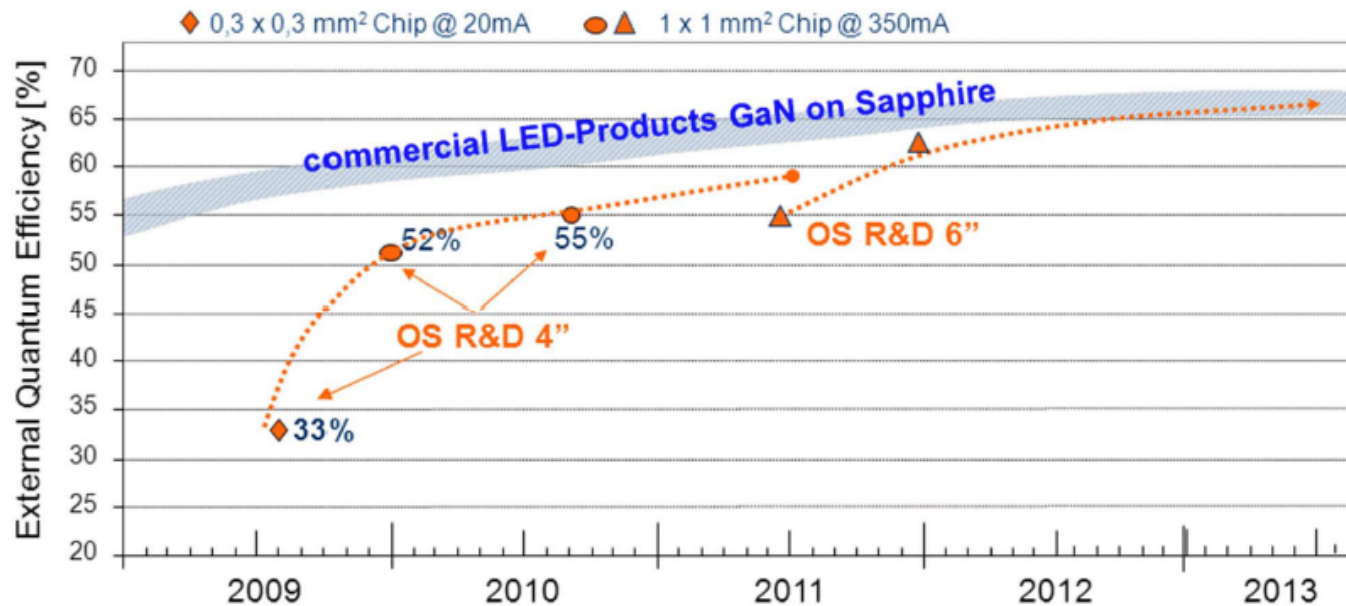
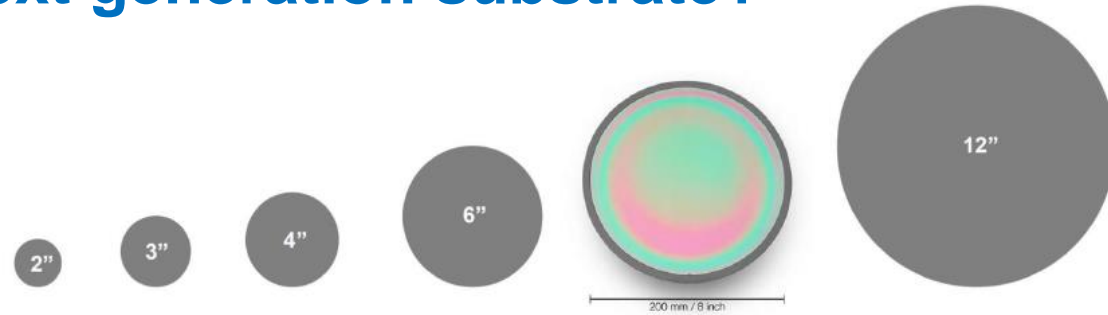
Droop curve:
$$IQE = \frac{R_{rad}}{R_{rad} + R_{nr}} = \frac{B_{rad} N^2}{A_{SRH}N + B_{rad}N^2 + C_{Auger}N^3}$$

R: recombination rates

N: carrier density in quantum well

LEDs – Challenges and perspectives

Silicon as next generation substrate?



Conclusion – Challenges and perspectives

Higher efficiency (limiting the efficiency droop)

Longer wavelengths

Cheaper fabrication process (NWRs, Si, new materials)

Better Light (CRI): UV LEDs + phosphors?